

ABSTRACT

AC-ground plane is for a semiconductor chip adapted to be mounted on a supporting member in a chip package, wherein said ground plane comprises at least one first capacitor plate provided within said chip, and at least one second capacitor plate provided on said supporting member, said first and second capacitor plate being separated by a dielectric layer and capacitively coupled to each other via this layer, and said ground plane comprising at least one first conducting member, said first conducting member being at least one electrically conducting via extending through said supporting member and electrically coupled in series with said second capacitor plate.

9 **Fig. 1**